

MSL98-002CCCIP_CIPB

appl. no. 10/783,195

B / Ifw

May 14, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/783,195 02/20/04

MOU-SHIUNG LIN ET. AL.

“POST PASSIVATION STRUCTURE FOR
SEMICONDUCTOR CHIP OR WAFER”

Grp. Art Unit: 2814

LE, THAO X

AMENDMENT AFTER ALLOWANCE

Dear Sir:

Please amend the above-identified application for patent and consider the remarks, as follows:

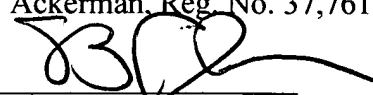
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 14, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date


May 14, 2008

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 10 of this paper.